

**FEATURES**

- Very Low Total Harmonic Distortion
- Lower Glitch Energy
- Four Quadrant Multiplication
- On-Chip Latches for Both DACs
- +10.8 V to +15.75 V Operation
- Low Power Consumption
- TTL/5V CMOS Compatible
- Latch-Up Free
- Second Source to AD7628
- 5 V Operation: MP7529B

BENEFITS

- Quiet Operation in Audio Applications
- Easy Interface to Microprocessors

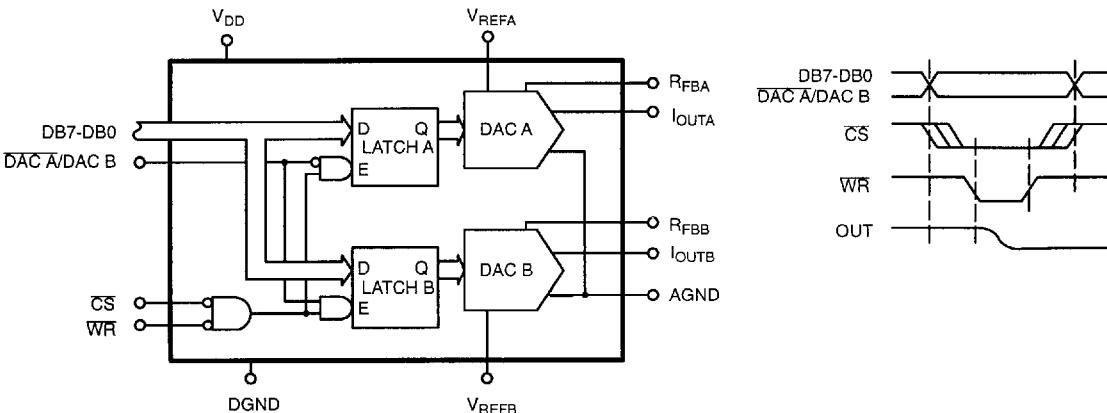
GENERAL DESCRIPTION

The MP7529A is a dual 8-bit Digital-to-Analog Converter featuring excellent DAC-to-DAC matching, tracking and specifically optimized for applications requiring low total harmonic distortion. The MP7529A is manufactured using advanced thin film resistors on a double metal CMOS process. The MP7529A incorporates a unique decoding technique yielding lower glitch energy, higher speed and excellent accuracy over temperature and time.

Data is transferred to either of the two D/A Converter latches via a common 8-bit TTL/5 V CMOS compatible input port. The control input DAC A/DAC B determines which DAC is to be loaded.

The device is specified for operation from +10.8 V to +15.75 V power supply, and is TTL-compatible over this range. Power dissipation is only 20 mW. Both DACs offer excellent four quadrant multiplication characteristics, and include separate reference inputs and feedback resistors. An improved latch-up resistant design eliminates the need for external protective Schottky diodes in most applications.

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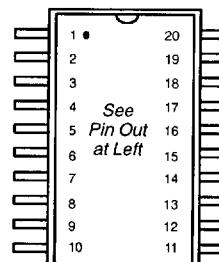
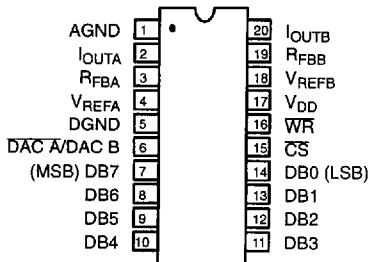
SIMPLIFIED BLOCK AND TIMING DIAGRAM

ORDERING INFORMATION

Package Type	Temperature Range	Part No.	INL (LSB)	DNL (LSB)	Gain Error (LSB)
Plastic Dip	-40 to +85°C	MP7529AJN	±1	±1	±5
Plastic Dip	-40 to +85°C	MP7529AKN	±1/2	±1	±3
SOIC	-40 to +85°C	MP7529AJS	±1	±1	±5
SOIC	-40 to +85°C	MP7529AKS	±1/2	±1	±3
PLCC	-40 to +85°C	MP7529AJP	±1	±1	±5
PLCC	-40 to +85°C	MP7529AKP	±1/2	±1	±3

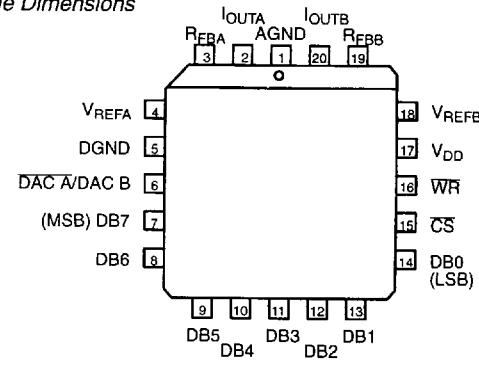
PIN CONFIGURATIONS

See Packaging Section for Package Dimensions



20 Pin PDIP (0.300")
N20

20 Pin SOIC (Jedec, 0.300")
S20



20 Pin PLCC
P20

PIN OUT DEFINITIONS

PIN NO.	NAME	DESCRIPTION
1	AGND	Analog Ground
2	IOUTA	Current Output of DAC A
3	RFBAA	Internal Feedback Resistor of DAC A
4	VREFFA	Reference Input Voltage of DAC A
5	DGND	Digital Ground
6	DAC A/ DAC B	DAC selection control
7	DB7	Data Input Input Bit 7 (MSB)
8	DB6	Data Input Bit 6
9	DB5	Data Input Bit 5
10	DB4	Data Input Bit 4

PIN NO.	NAME	DESCRIPTION
11	DB3	Data Input Bit 3
12	DB2	Data Input Bit 2
13	DB1	Data Input Bit 1
14	DB0	Data Input Bit 0 (LSB)
15	CS	Chip Select (Active Low)
16	WR	Write Enable (Active Low)
17	VDD	Power Supply
18	VREFB	Reference Input Voltage of DAC B
19	RFBBA	Internal Feedback Resistor of DAC B
20	IOUTB	Current Output of DAC B

ELECTRICAL CHARACTERISTICS

(V_{DD} = +10.8 V to +15.75, V_{REF} = +10 V unless otherwise noted)

Parameter	Symbol	Min	25°C Typ	Max	Tmin to Tmax Min Max	Units	Test Conditions/Comments
STATIC PERFORMANCE¹							
Resolution (All Grades)	N	8			8	Bits	
Integral Non-Linearity (Relative Accuracy) J K	INL				±1 ±1/2	LSB	End Point Linearity Spec.
Differential Non-Linearity J K	DNL				±1 ±1	LSB	All grades monotonic over full temperature range.
Gain Error J K	GE				±4 ±2	LSB	Using Internal R _{FB}
Gain Temperature Coefficient ²	TC _{GE}		±15			ppm/°C	ΔGain/ΔTemperature
Power Supply Rejection Ratio	PSRR			±100		ppm/%	ΔGain/ΔV _{DD} , ΔV _{DD} = ± 5% V _{DD} = 10.8 V, ±5%, & 15.75 V ±5%
Output Leakage Current	I _{LKG}			±50		nA	
DYNAMIC PERFORMANCE²							
Harmonic Distortion	THD		-95			dB	
Digital Crosstalk	Q		30			nVs	V _{IN} = 6V _{RMS} @ 1 kHz
AC Feedthrough	F _T					dB	
V _{REFA} to I _{OUTA}	F _{TA}		-70			dB	
V _{REFB} to I _{OUTB}	F _{TB}		-70			dB	
Channel-to-Channel Isolation	CCI					dB	
V _{REFA} to I _{OUTB}	C _{CIBA}		-77			dB	
V _{REFB} to I _{OUTA}	C _{CIAB}		-77			dB	
Glitch Energy	Egl		10			dB	
Current Settling Time	t _S		200			nVs	All zeros to all ones Input Change To 1/2 LSB, R _L =100Ω, C _{EXT} =13pF
Propagation Delay	t _{PD}		100		250 150	ns ns	From 50% of digital input to 90% of final analog output current R _L =100Ω, C _{EXT} =13pF
REFERENCE INPUT¹							
Input Resistance	R _{IN}	8		15	8	kΩ	
Input Resistance Matching			±1		15 ±1	%	
DIGITAL INPUTS³							
Logical "1" Voltage	V _{IH}	3.0	2.4		3.0	V	
Logical "0" Voltage	V _{IL}			0.8	0.8	V	
Input Leakage Current	I _{LKG}			±1	±10	μA	
Input Capacitance ² Data Control	C _{IN} C _{IN}			10 15	10 15	pF pF	

ELECTRICAL CHARACTERISTICS (CONT'D)

Parameter	Symbol	Min	25°C Typ	Max	Tmin to Tmax Min Max	Units	Test Conditions/Comments
ANALOG OUTPUTS²							
Output Capacitance	C _{OUTA/B} C _{OUTA/B}		120 50		120 50	pF pF	DAC inputs all 1's DAC inputs all 0's
POWER SUPPLY¹							
Supply Current	I _{DD}		1 2		1 2	mA mA	All digital inputs = 0 V, or all = 5 V All digital inputs = V _{IL} , or all = V _{IH}
TIMING SPECIFICATIONS⁴							
Chip Select to Write Set-Up Time	t _{CS}	60			80		ns
Chip Select to Write Hold Time	t _{CH}	15			20		ns
DAC Select to Write Set-Up Time	t _{AS}	60			80		ns
DAC Select to Write Hold Time	t _{AH}	15			20		ns
Data Valid to Write Set-Up Time	t _{DS}	60			80		ns
Data Valid to Write Hold Time	t _{DH}	0			0		ns
Write Pulse Width ⁵	t _{WR}	60			80		ns

NOTES:

- 1 Full Scale Range (FSR) is 10V for unipolar mode.
- 2 Guaranteed but not production tested.
- 3 Digital input levels should not go below ground or exceed the positive supply voltage, otherwise damage may occur.
- 4 See timing diagram Figure 1.
- 5 t_{WR} = 40ns minimum if t_{DH} > 15ns (@T = 25°C).

Specifications are subject to change without notice

ABSOLUTE MAXIMUM RATINGS (TA = +25°C unless otherwise noted)^{1, 2, 3}

V _{DD} to GND	GND -0.5 to +17 V	V _{RFBA} , V _{RFBB} to GND	±25 V
AGND to DGND	±1 V	Storage Temperature	-65°C to +150°C
(Functionality Guaranteed ±0.5 V)		Lead Temperature (Soldering, 10 seconds)	+300°C
Digital Input Voltage to GND	GND -0.5 V to +7 V	Package Power Dissipation Rating to 75°C	
I _{OUTA} , I _{OUTB} to GND	GND -0.5 V to +7 V	PDIP, SOIC, PLCC	900mW
V _{REFA} , V _{REFB} to GND	±25 V	Derates above 75°C	12mW/ ^o C

NOTES:

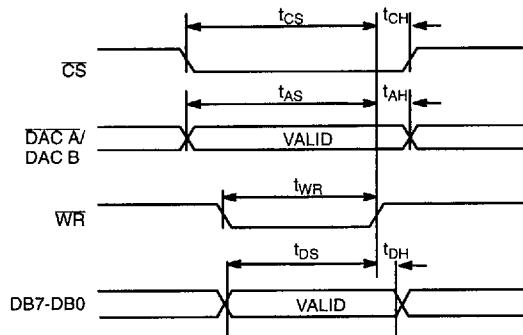
- 1 Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
- 2 Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies. All inputs have protection diodes which will protect the device from short transients outside the supplies of less than 100mA for less than 100μs.
- 3 GND refers to AGND and DGND.

DIGITAL INTERFACE

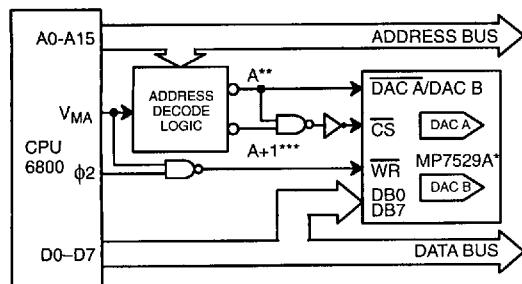
The digital inputs are designed to be both TTL and 5 V CMOS compatible. All logic inputs are static protected MOS gates with typical input currents of less than 10nA.

The control input DAC A/DAC B selects which DAC can accept data from the input port. Inputs CS and WR control the operating mode of the selected DAC (Table 1.). When CS and WR

are both low the selected DAC is in the write mode. The input data latches of the selected DAC are transparent and its analog output responds to activity on DB0-DB7 (Write mode). The selected DAC latch retains the data which was present on DB0-DB7 just prior to CS or WR assuming a high state. Both analog outputs remain at the values corresponding to the data in their respective latches (Hold mode).

**NOTE:**

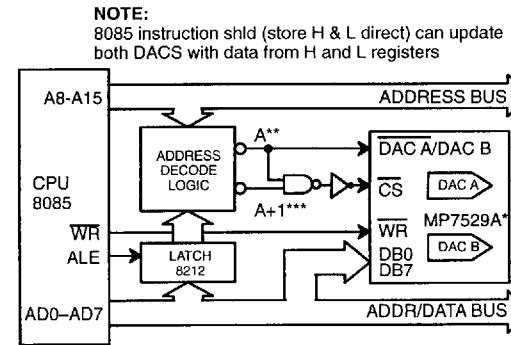
1. Timing measured from $(V_{IH} + V_{IL}) / 2$

Figure 1. Write Cycle Timing Diagram**Table 1. DACs Mode Selection****MICROPROCESSOR INTERFACE**

*Analog circuitry has been omitted for clarity

**A = Decoded 7529A DAC A Address

***A+1 = Decoded 7529A DAC B Address

Figure 2. MP7529A Dual DAC to 6800 CPU Interface

*Analog circuitry has been omitted for clarity

**A = Decoded 7529A DAC A Address

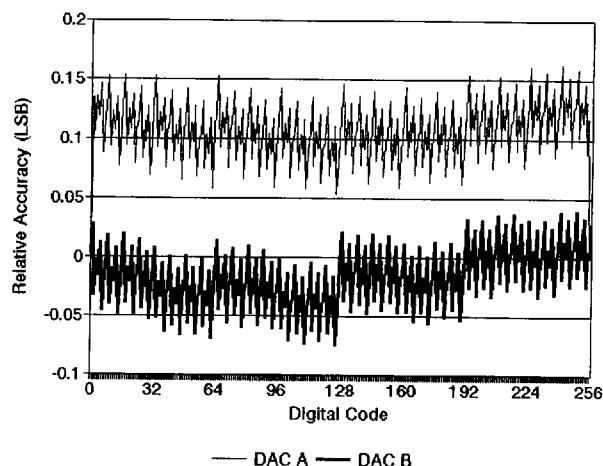
***A+1 = Decoded 7529A DAC B Address

Figure 3. MP7529A Dual DAC to 8085 CPU Interface

MP7529A

EXAR

PERFORMANCE CHARACTERISTICS



Graph 1. Relative Accuracy vs. Digital Code

APPLICATION NOTES

Refer to Section 8 for Applications Information